

## HM50N06D-VB Datasheet

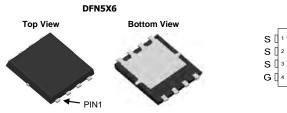
# N-Channel 60 V (D-S) MOSFET

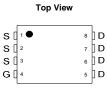
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	V <sub>DS</sub> (V) R <sub>DS(on)</sub> (Ω)			
60	0.006 at V <sub>GS</sub> = 10 V	80		
	0.007 at V <sub>GS</sub> = 4.5 V	65		

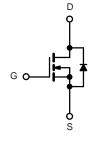
#### FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:









N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ( $T_{C}$ =	= 25 °C, unless othe	rwise noted)		
Parameter	Symbol	Limit	Unit	
Gate-Source Voltage	V <sub>GS</sub>	± 20	V	
	T <sub>C</sub> = 25 °C	1-	80	
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 100 °C	I <sub>D</sub>	65 <sup>a</sup>	
Pulsed Drain Current	I <sub>DM</sub>	100	А	
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	70 <sup>a</sup>		
Avalanche Current	I <sub>AS</sub>	50		
Single Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ
Mavimum Dawar Discinction	T <sub>C</sub> = 25 °C	P	136	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub> —	3 <sup>b</sup> , 8.3 <sup>b, c</sup>	vv
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	$t \le 10 \text{ sec}$	- R <sub>thJA</sub>	15	18		
Maximum Junction-to-Ambient*	Steady State		40	50	°C/W	
Maximum Junction-to-Case		R <sub>thJC</sub>	0.85	1.1		

Notes:

a. Package limited.

c.  $t \le 10$  s.

b. Surface mounted on 1" x 1" FR4 board.

Parameter	Symbol	Test Conditions	Min.	Tun a	Max.	Unit	
	Symbol	Test conditions	wiin.	Typ. <sup>a</sup>	wax.	Unit	
Static	N N						
Drain-Source Breakdown Voltage			60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2.5		4		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V$ , $V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50	μA	
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	60			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.006			
- ·	D D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C	0.010			Ω	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.015			
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A	0.007				
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S	
Dynamic				1			
Input Capacitance	C <sub>iss</sub>			2650			
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		470		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			225			
Total Gate Charge <sup>c</sup>	Qg			47	70		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_{D}$ = 50 A		10		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12		1	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, \text{ R}_{L} = 0.6 \Omega$		15	25	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_a = 2.5 \Omega$		35	50		
Fall Time <sup>c</sup>	t <sub>f</sub>	Ŭ		20	30		
Source-Drain Diode Ratings and Cha	aracteristics (	$T_{\rm C} = 25 ^{\circ}{\rm C}$					
Pulsed Current	I <sub>SM</sub>				60	А	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		1	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/µs		45	100	ns	

Notes:

a. For design aid only; not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. Independent of operating temperature.

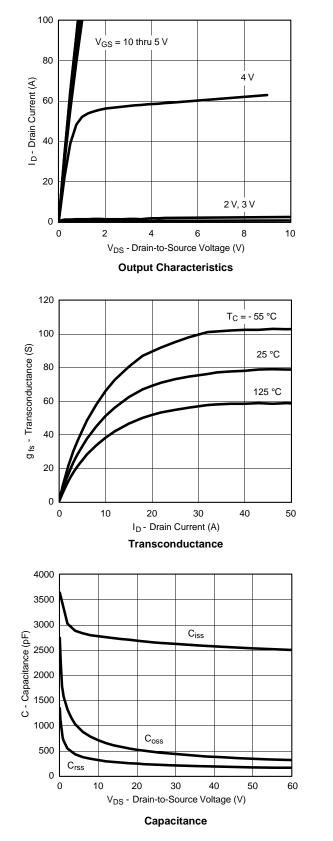
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

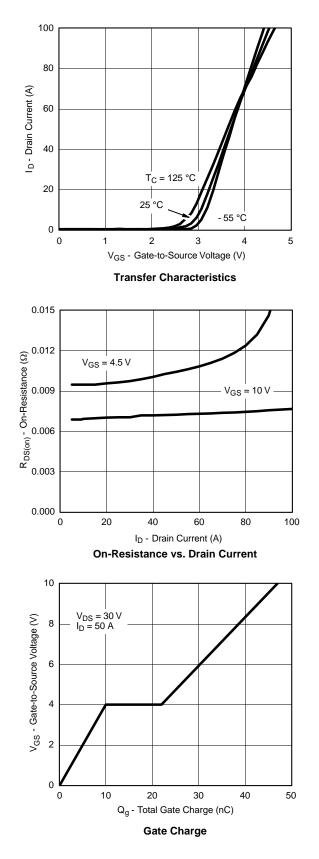
Bsemi

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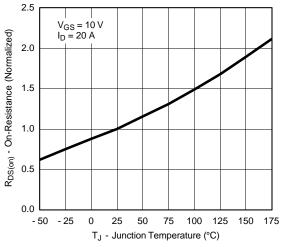
#### TYPICAL CHARACTERISTICS (25 °C unless noted)



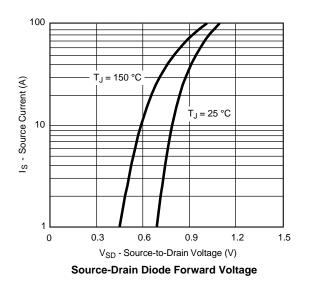




### TYPICAL CHARACTERISTICS (25 °C unless noted)

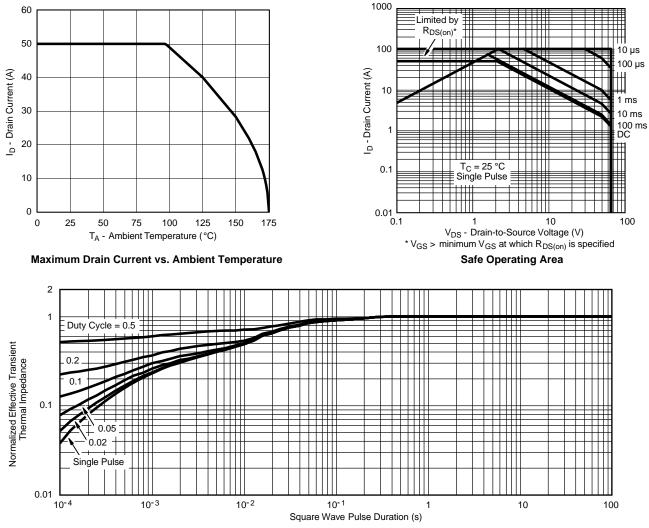


**On-Resistance vs. Junction Temperature** 



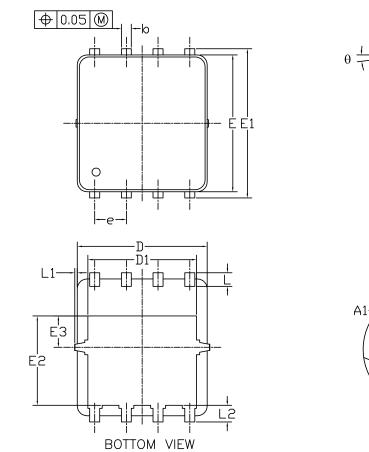


#### **THERMAL RATINGS**

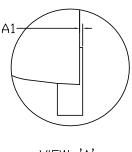


Normalized Thermal Transient Impedance, Junction-to-Case





DFN5x6\_8L\_EP1\_P PACKAGE OUTLIN



Α

С

VIEW 'A'

<u>VIEW 'A'</u> (SCALE 5:1)

**RECOMMENDED LAND PATTERN** .60 -0.55 0.50 -0.77 -0.635 4.12 6.15 -1.60 + + 0.65 +|+| ŧ -11.27-0.50-

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
STNBOLS	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.85	0.95	1.00	0.033	0.037	0.039
A1	0.00		0.05	0.000		0.002
b	0.30	0.40	0.50	0.012	0.016	0.020
с	0.15	0.20	0.25	0.006	0.008	0.010
D	5.10	5.20	5.30	0.201	0.205	0.209
D1	4.25	4.35	4.45	0.167	0.171	0.175
E	5.45	5.55	5.65	0.215	0.219	0.222
E1	5.95	6.05	6.15	0.234	0.238	0.242
E2	3.525	3.625	3.725	0.139	0.143	0.147
E3	1.175	1.275	1.375	0.046	0.050	0.054
e		1.27 BSC			0.050 BSC	
L	0.45	0.55	0.65	0.018	0.022	0.026
L1	0		0.15	0		0.006
L2	0.68 REF			0.027 REF		
θ	0°		10°	0°		10°

NOTE

UNIT: mm

 PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
CONTROLLING DIMENSION IS MILLIMETER.

CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.



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